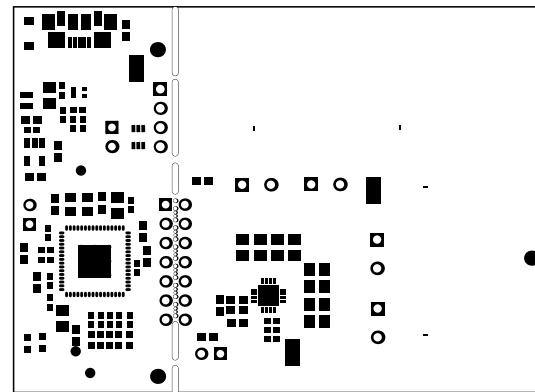
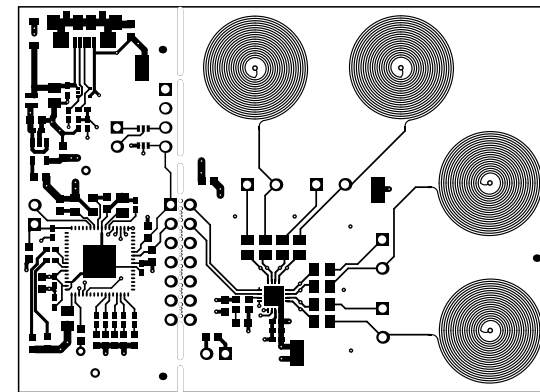


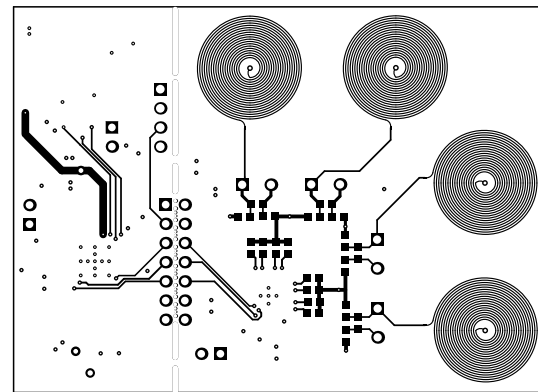
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
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PLOT NAME = Top Overlay	GENERATED : 2017/8/4 21:16:59	TEXAS INSTRUMENTS	



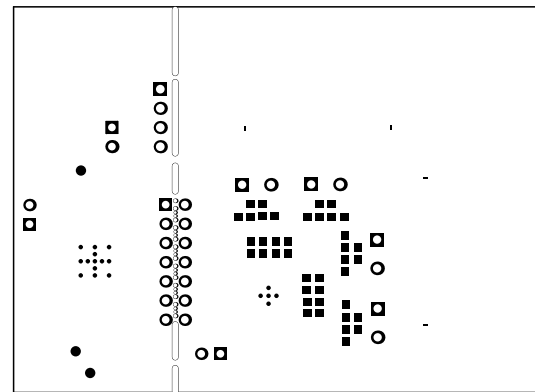
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01465		
PLOT NAME = Top Solder Mask	GENERATED : 2017/8/4 21:17:00	TEXAS INSTRUMENTS	



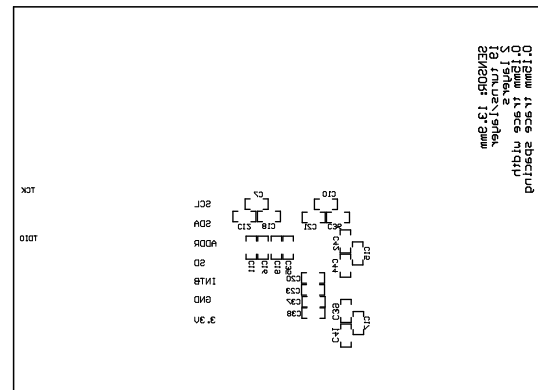
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01465		
PLOT NAME = Top Layer	GENERATED : 2017/8/4 21:17:01	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01465		
PLOT NAME = Bottom Layer	GENERATED : 2017/8/4 21:17:02	TEXAS INSTRUMENTS	

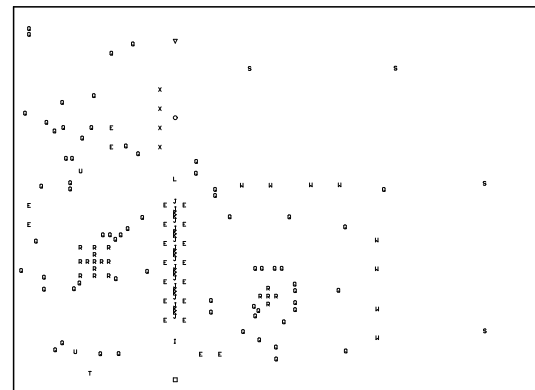


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01465		
PLOT NAME = Bottom Solder Mask	GENERATED : 2017/8/4 21:17:03	TEXAS INSTRUMENTS	

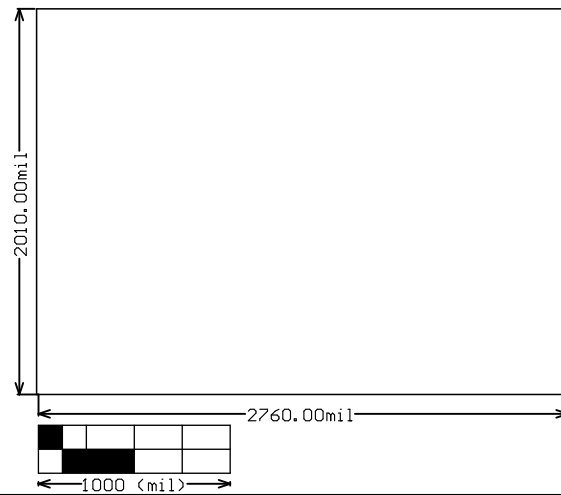


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 REVISION: 1.3.2017

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01465		
PLOT NAME = Bottom Overlay	GENERATED : 2017/8/4	21:17:04	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01465		
PLOT NAME = Drill Drawing	GENERATED : 2017/8/4	21:17:05	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01465	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01465		
PLOT NAME = Board Dimensions	GENERATED : 2017/8/4	21:17:06	TEXAS INSTRUMENTS

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